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APPLICATION NO.		FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/706,212		11/12/2003	Michael E. Connell	5083.1US (01-0428.01/US)	6326
24247	7590	10/07/2005		EXAM	INER .
TRASK B			WILSON, ALLAN R		
P.O. BOX 2550 SALT LAKE CITY, UT 84110				ART UNIT	PAPER NUMBER
	ŕ			2815	
				DATE MAILED: 10/07/2005	5

Please find below and/or attached an Office communication concerning this application or proceeding.

<u>.</u>		Application No.	Applicant(s)		
		10/706,212	CONNELL ET AL.		
	Office Action Summary	Examiner	Art Unit		
		Allan R. Wilson	2815		
<u>-</u>	The MAILING DATE of this communication a		the correspondence address		
	or Reply				
WHI - Exte afte - If N - Fail Any	HORTENED STATUTORY PERIOD FOR REF CHEVER IS LONGER, FROM THE MAILING ensions of time may be available under the provisions of 37 CFR or SIX (6) MONTHS from the mailing date of this communication. O period for reply is specified above, the maximum statutory periure to reply within the set or extended period for reply will, by state reply received by the Office later than three months after the manned patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNICATION 1.136(a). In no event, however, may a report of will apply and will expire SIX (6) MONTH tute, cause the application to become ABAI	ATION. ly be timely filed HS from the mailing date of this communication. NDONED (35 U.S.C. § 133).		
Status			ſ		
1)	Responsive to communication(s) filed on 23	R August 2005.	•		
2a)□	-	his action is non-final.			
3) Since this application is in condition for allowance except for formal matters, prosecution as to					
ŕ	closed in accordance with the practice unde	er Ex parte Quayle, 1935 C.D.	11, 453 O.G. 213.		
Disposit	tion of Claims				
· ·	Claim(s) <u>1-24</u> is/are pending in the application	on			
4)23	4a) Of the above claim(s) is/are withd				
5)	Claim(s) is/are allowed.				
-	Claim(s) <u>1-24</u> is/are rejected.				
	Claim(s) is/are objected to.				
8)□	Claim(s) are subject to restriction and	d/or election requirement.			
Applicat	tion Papers				
	The specification is objected to by the Exami	iner			
,	The drawing(s) filed on is/are: a) _ a		the Examiner.		
,,	Applicant may not request that any objection to the				
	Replacement drawing sheet(s) including the corr				
11)	The oath or declaration is objected to by the	Examiner. Note the attached	Office Action or form PTO-152.		
Priority	under 35 U.S.C. § 119	·			
-	Acknowledgment is made of a claim for forei	gn priority under 35 U.S.C. § 1	19(a)-(d) or (f).		
a)	 All b) Some * c) None of: 1. Certified copies of the priority docume 	ante have been received			
	1. Certified copies of the priority docume2. Certified copies of the priority docume		olication No		
	3. Copies of the certified copies of the pi				
	application from the International Bure	•	200700 III tillo Mattorial Grago		
*	See the attached detailed Office action for a li	, , , , , , , , , , , , , , , , , , , ,	eceived.		
	•	·			
Attachmei	nt(s)				
1) 🔲 Noti	ce of References Cited (PTO-892)		nmary (PTO-413)		
	ce of Draftsperson's Patent Drawing Review (PTO-948)	_	Mail Date brmal Patent Application (PTO-152)		
	mation Disclosure Statement(s) (PTO-1449 or PTO/SB/0er No(s)/Mail Date	6) Other:			

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DETAILED ACTION

Claim Objections

Claim 19 is objected to because of the following informalities:

Claim 19 recites the limitation "the stress-balancing layer" in line 8. There is insufficient antecedent basis for this limitation in the claim.

Appropriate correction is required.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1-24 are rejected under 35 U.S.C. 102(e) as being anticipated by 2003/0017652 to Sakaki et al. Regarding claims 1, 7, 13 and 19, Sakaki teaches in figure 3 a semiconductor die comprising:

a semiconductor substrate 1 having a front side 1B and a back side 1A and having a low ratio of height to horizontal dimension (see fig. 2);

an integrated circuit on a portion of the front side (note that the front side is also labeled 1X which is designated the "circuit formation surface");

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a passivation layer 7 (resin, para. 0096) covering a portion of the integrated circuit causing a stress on at least a portion of the substrate; and

a stress or force balancing layer 2 covering at least a portion of the backside substantially balancing the stress caused by the passivation layer covering a portion of the integrated circuit (see paras. 0106 and 0107, esp. 0107 at the third sentence *et. seq.*, which teach that layer 7 causes a stress which is compensated by layer 2), the stress or force balancing layer comprising at least one of a tape material (2 in FIG. 8) and an adhesive material (paragraph 127, layer 2 is thermally adhered to substrate 1). Additionally, "a chemical vapor deposition material" and "a physical vapor deposition material" are product by process limitations (see MPEP 2113).

Regarding claims 2-4, 8-10, 14-16 and 20-22, Sakaki teaches that the balancing layer is a resin, which may be considered either a single component layer or a homogenous mixture of a strong material, is an adhesive (as it adheres to substrate 1) and may be marked by a laser (an intended use). Regarding claims 5, 6, 11, 12, 17, 18, 23 and 24, Sakaki teach in figure 9 an adhesive layer 41A attached to the stress-balancing layer 2 (para. 0136), which adhesive layer may be marked by a laser (an intended use).

Response to Arguments

Applicant's arguments filed 08/04/2005 have been fully considered but they are not persuasive.

The argument that Sakaki reference does not describe the elements calling for the stress or force balancing layer comprising at least one of a tape material and an adhesive material is not persuasive. Sakaki clearly illustrates in FIG. 8 and describes in paragraphs 123-134 the stress or

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force balancing layer 2 comprising a tape material. Particularly paragraph 132 discloses "a resin film 2 and a spacer tape 36 from a reel 35A." Sakaki also disclose in paragraph 127 "a sticking unit for sticking a resin film 2 on the back surface of the semiconductor wafer by thermal crimping." The resin film adheres to the wafer when heated by a heating roller 31A. Therefore, the resin film 2 is a thermally activated adhesive material.

Any inquiry concerning this communication or earlier communications from an examiner should be directed to Primary Examiner Allan Wilson whose telephone number is (571) 272-1738. Examiner Wilson can normally be reached 7:00-4:00 Monday-Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Primary Examiner 29 September 2005